



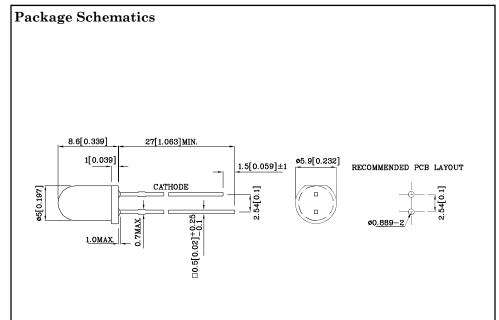


Features

- Radial / Through hole package
- \bullet Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS Compliant







Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		M2ACY (AlGaInP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA	
Power Dissipation	P_{D}	75	mW	
Operating Temperature	T_A -40 ~ +85		°C	
Storage Temperature	Tstg	-40 ~ +85	C	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds			
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds			

Operating Characteristics (T _A =25°C)		M2ACY (AlGaInP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	2	V	
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V	
Reverse Current (Max.) $(V_R=5V)$	I_R	10	uA	
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λΡ	590*	nm	
Wavelength of Dominant Emission CIE127-2007* (Typ.) $(I_F=20\text{mA})$	λD	590*	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	20	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	45	pF	

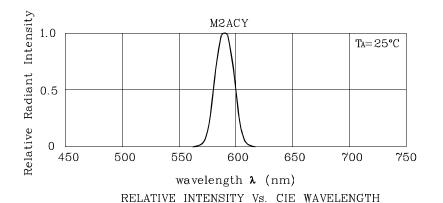
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} \text{Luminous Intensity} \\ \text{CIE127-2007*} \\ \text{(I}_{\text{F}}\text{=20mA)} \\ \text{mcd} \end{array}$		Wavelength CIE127-2007* nm λΡ	Viewing Angle 20 1/2
				min.	typ.		
XLM2ACY12W	Yellow	AlGaInP	Water Clear	4200* 5	5990*	590*	20°

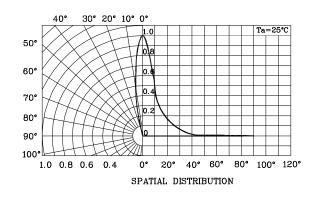
 $^{^*}$ Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

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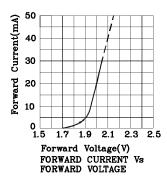


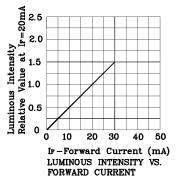


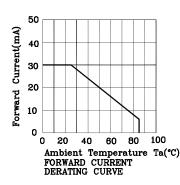


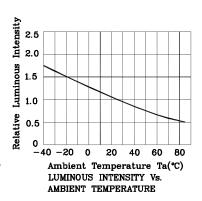


❖ M2ACY

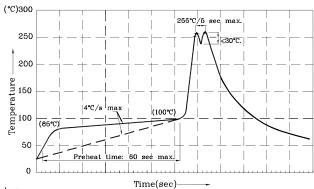








Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

- Notes. I. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of $260^{\circ}C$ 2. Peak wave soldering temperature between $245^{\circ}C \sim 255^{\circ}C$ for 3 sec
- (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above $85\,^\circ\text{C}.$ 4.Fixtures should not incur stress on the component when mounting and
- during soldering process. 5.SAC 305 solder alloy is recommended.
- 6. No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

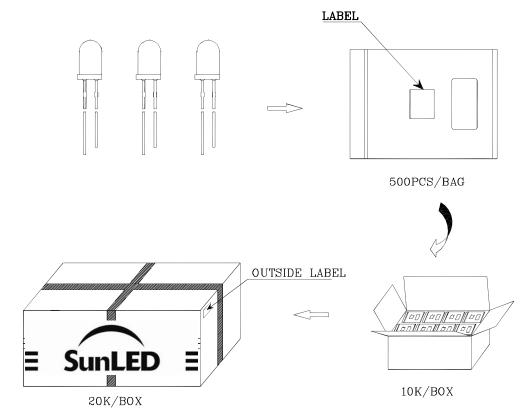
the typical accuracy of the sorting process is as follows:

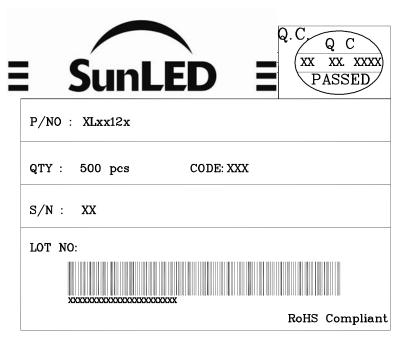
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS





TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp

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